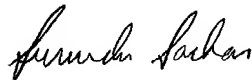


By the present response Claims 4 and 6 are cancelled and Claims 1 and 5 are amended. Amended Claim 1 is believed to be generic to any species, and each of currently pending Claims 1, 2, 3, and 5 are believed to read on a single species.

The present application is believed to be in condition for a full and thorough examination on the merits. An early and favorable consideration of the present application is hereby respectfully requested.

Respectfully submitted,

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Marked-Up Copy
Serial No: 091899,156
Amendment Filed on: 5-30-02

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IN THE CLAIMS

- 1. (Amended) A printed wiring board, comprising:
- an insulating layer having a first surface and a second surface located on the opposite side of said first surface;
 - a plurality of wiring layers formed so as to correspond to a predetermined circuit pattern, said wiring layers [being formed by etching metal foils laminated on said first surface and said second surface of said insulating layer, respectively] being laminated at least on said first surface and said second surface of said insulating layer;
 - a via formed on said insulating layer, said via having one end opened on said first surface of said insulating layer and the other end closed by said wiring layer [formed on said second surface of said insulating layer] laminated on a part of said insulating layer other than said first surface;
 - a first plating layer, said first plating layer continuously covering said inner surface of said via, said wiring layer [formed on said second surface] exposed within said via and that portion of the wiring layer which is formed on said first surface and which faces one end of said via; and
 - a second plating layer, said second plating layer being laminated on said first plating layer, electrically connecting said wiring layer formed on said first surface and said wiring

layer [formed on said second surface] laminated on the part of said insulating layer other than said first surface by cooperating with said first plating layer.

4. (Cancelled).

5. (Amended) The printed wiring board according to claim [4] 1, wherein [said first plating layer is a conductive substrate] said insulating layer and said wiring layers form a laminate, and one of said wiring layers is formed inside said insulating layer, is exposed within said via, and is covered by said first plating layer.--

6. (Cancelled).